

FinalPrep Alumina Solution

FinalPrep is a de-agglomerated, polycrystalline alumina solution excellent for final polishing applications for nearly any material. With a pH of 9 to 9.5, the basic chemical element enhances microstructural features. It works exceptionally well for polishing soft, ductile, or precious metals, such as gold (Au) and silver (Ag).

It provides an excellent surface finish on many materials, including, but not limited to, those listed in Table 1.



Table 1: FinalPrep Uses

Group	Examples *	Recommended Cloths
Precious Metals	Gold, Silver, Platinum, Iridium	DiaMat, Final P
Electronic Materials	Packages, Gold Bond Wires, ICs, LEDs, Semiconductors, Circuit Boards	Final A, Red Final C, Final P
Ferrous Metals	Carbon Steels, Iron, Stainless Steels	Chem-Pol, Final-Pol
Non-Ferrous Metals	Copper, Titanium, Aluminum, Lead, Zinc, Cobalt, Nickel, and Lead Based Alloys	Chem-Pol, Final P

*Figures 1 through 8 are micrographs of various samples prepared with FinalPrep.

FinalPrep should be shaken well before use to mix any settled abrasive. It can be applied manually or with automatic “drip” dispensing systems.

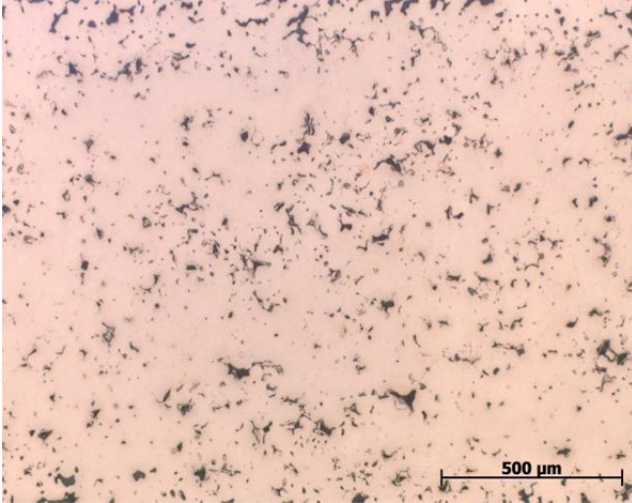


Figure 1: Porous copper, as-polished, 10X objective, Brightfield

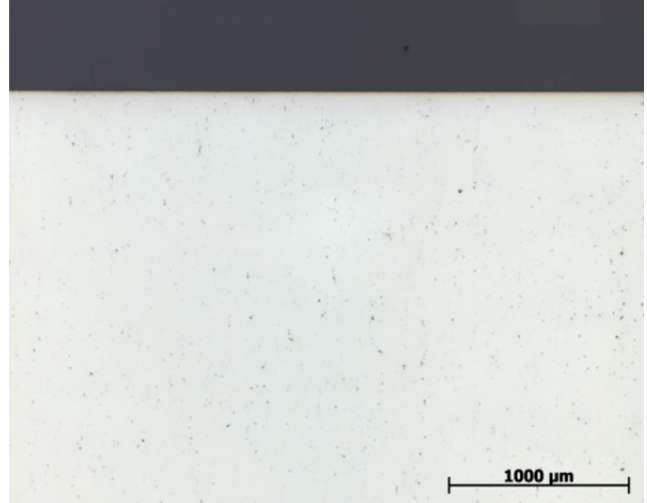


Figure 2: Aluminum 5083-H116, as-polished, 5X objective, Brightfield

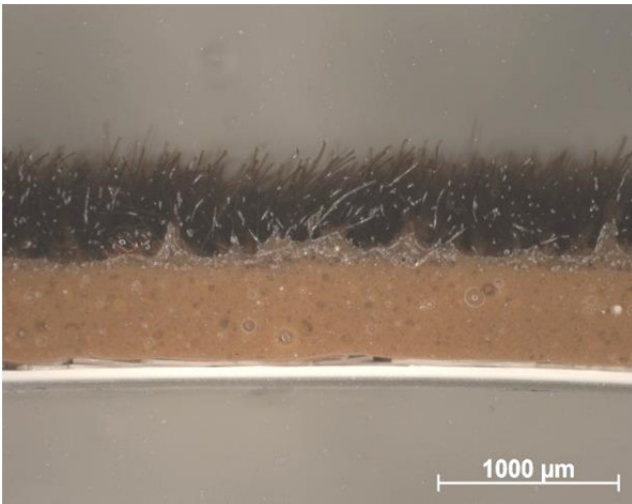


Figure 3: Encapsulated synthetic flocked foam, as-polished, 5X objective, Darkfield

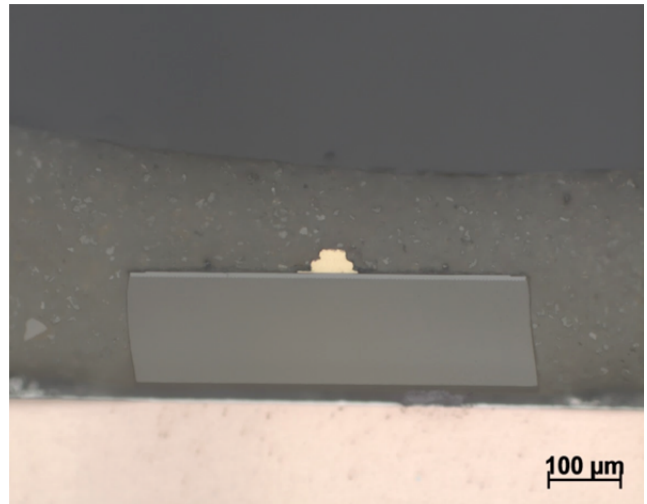


Figure 4: Silicone package, as-polished, 20X objective, Brightfield

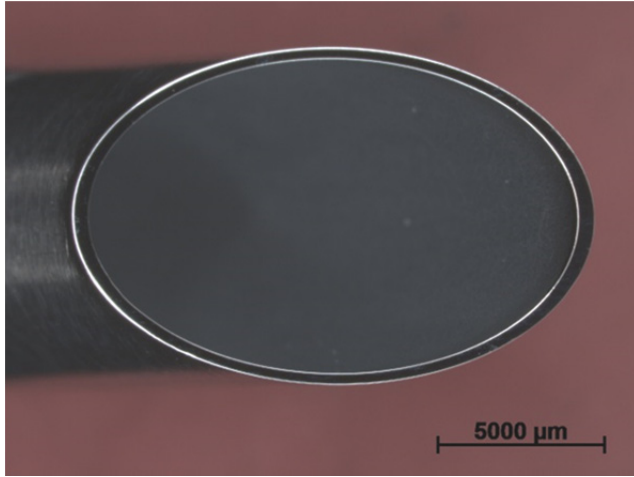


Figure 5: Stainless steel tube section, as-polished, Discovery V20 stereomicroscope



Figure 6: Steel sleeve bearing with copper and Teflon coatings, as-polished, 2.5X objective, Brightfield

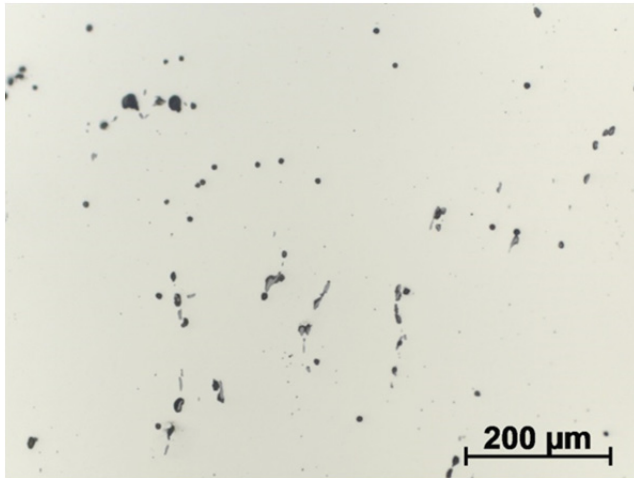


Figure 7: Quenched and tempered steel alloy 4140, as-polished, 20X objective, Brightfield



Figure 8: Inconel X750 wire, as-polished, 20X objective, C-DIC